

04-29-1999



Docket No. JCLA3897

101023688

Form 1595
1-31-92

RECORDATION FORM COVER SHEET

U.S. Department of Commerce
Patent and Trademark Office

PATENTS ONLY

To the Honorable Assistant Commissioner for Patents: Please record the attached
original documents or copy thereof.

1. Name of conveying party(ies):

Yen-Lin Ding
Gary Hong2. Name/address of receiving
Party(ies):

United Semiconductor Corp.

No 3, Li-Hsin Rd. II, Science-Based
Industrial Park, Hsinchu,
Taiwan, R.O.C.3. Nature of conveyance: ☒ Assignment☐ Merger ☐ Security Agreement ☐ Other☐ Change of Name ☐ Reassignment

Add'l names of receiving parties

4. Date(s) of execution: March 24, 1999

Attached? ☐ Yes ☒ No

5. Application number(s) or patent number(s):

**If this documents is being filed together with a new application, the
execution date of the application is March 24, 1999**

A. Patent Application No. (s)

B. Patent No. (s)

Additional numbers attached ? ☐ Yes ☒ No6. Name and address of party to whom
correspondence concerning document
should be mailed:J.C. Patents, Inc.
1340 Reynolds Ave., Suite 114
Irvine, CA 92614
(949) 660-07617. Total No. of applications and patents
involved:

ONE(1)

8. Total fee (37 CFR §3.41): \$40.00

☒ Enclosed☐ Charge to Acct. No.9. Total number of pages, including
cover sheet, attachments and document 3.

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10. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true
and correct and any attached copy is a true copy of the original document.Jiawei Huang
Name of Person Signing

Signature

Date

Registration No. 43, 330

JCL530 U.S. PTO
09/29/99

04/16/99

04/26/1999 JSHAMAZZ 00000180 09293434

01 FC:581

40.00 00

PATENT

REEL: 9907 FRAME: 0927

ASSIGNMENT

WHEREAS,

1. Yen-Lin Ding

2. Gary Hong

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FORMING A STACKED GATE**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Semiconductor Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Yen-Lin Ding
Sole or First Joint Inventor: Yen-Lin Ding

Date: March 24 '99

Signature: Gary Hong
Second Joint Inventor (if any) Gary Hong

Date: March 24 1999